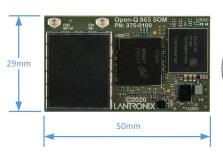


# Open-Q<sup>™</sup> 865XR SOM (System on Module)

Based on the Qualcomm® SXR2130P processor







# Horsepower at the Edge

- The 865XR SOM offers the perfect computing core for a variety of leading edge IoT applications
- The ideal solution to accelerate your "time to revenue" on product development
- The Qualcomm® AI Engine provides 2x the performance of the previous generation with up to 15 TOPS

The Open-Q™ 865XR SOM is an ultra-compact (50mm x 29mm) production-ready, pre-certified SOM based on the powerful Qualcomm SXR2130P SoC. The 865XR utilizes Qualcomm® Technologies' heterogenous compute expertise to offer a System-on-Chip with multiple specialized processing cores:

- · 5th generation Qualcomm® AI Engine
- Qualcomm Spectra<sup>™</sup> ISP, Qualcomm<sup>®</sup> Adreno<sup>™</sup> GPU, and Qualcomm<sup>®</sup> Hexagon<sup>™</sup> DSP
- · Power, processing and professional quality imaging
- Coupled with the latest Wi-Fi 6 connectivity, advanced camera features, and many highspeed interfaces

#### **Key Features**

- Qualcomm SXR2130P processor
- 6GB LPDDR5 RAM + 64GB UFS 3.1 Flash
- 3x MIPI CSI camera ports
- 2x MIPI DSI display ports
- 1x 2-lane PCIe Gen3 interface
- USB Type-C with DisplayPort v1.4
- · Pre-certified Wi-Fi and Bluetooth
- Wi-Fi 6 802.11ax 2x2 MU-MIMO Wi-Fi / BT 5.1

#### **Applications**

- Al box—multi-stream encode/decode/Al processing
- · Video conference systems
- · Multi-camera systems
- · Machine vision platforms
- Advanced high resolution multi-display systems
- Medical imaging
- · Handheld data collectors

### **Engineering Services:**

We provide a full solution – our unparalleled engineering expertise and product development skills deliver innovative products that are cost-effective and can jumpstart your Go-to-Market timeline.

Our business model offers turnkey product development services, or we can augment your team in specific areas of development. The choice is yours.

#### Key development expertise in:

- · Camera development and tuning
- Voice control
- Machine learning
- Mechanical & RF design
- Thermal & power optimization

IoT Product Development made easy

# Qualcom





# Lantronix Open-Q<sup>™</sup> 865XR SOM

#### **Hardware Specifications:**

• Processors	Qualcomm <sup>*</sup> SXR2130P SoC built on 7nm technology: Kryo™ 585 Octa-core CPU: 1Kryo Gold prime @ 2.84 GHz + 3 Kryo Gold @ 2.42 GHz + 4 Kryo Silver @ 1.81 GHz Hexagon DSP with quad Hexagon Vector eXtensions		
	Adreno 650 GPU @ Fmax = 587 MHz Qualcomm Spectra 480 Image Signal Processor Adreno 665 Video Processing unit	Adreno 995 Display Processing unit NPU230 Neural Processing unit SPU240 Secure Processing unit	
• Memory/Storage	6GB or 8GB LPDDR5 RAM @ 2750MHz, 64GB UFS 2.1 or 128GB UFS 3.0		
• Wireless	Pre-certified for FCC, ISED (Canada), RED (EU) 802.11ax 2x2 MU-MIMO + Bluetooth 5.1, Bluetooth Milan ready		
• Display Interfaces	Up to three 4K displays (1 internal display through DSI and 2 external displays through DisplayPort) 2x 4-lane MIPI DSI D-PHY 1.2, up to 5040 × 2160 @ 60 fps (or 120 Hz in VR mode) + touchscreen support DisplayPort v1.4 on USB Type-C, at 8.1 Gbps/lane, with USB3 and USB2 data concurrency		
Camera Interfaces	3x 4-lane MIPI CSI camera ports + CCI I2C control	Qualcomm Spectra 480 ISP supporting multiple concurrent cameras 64 MP 30 fps ZSL with a dual ISP	
Video Performance	Video decode up to 4K240/8K60 Video encode up to 4K120/8K30	Concurrent 4K60 decode & 4K30 encode for wireless display	
• Audio	Supports WCD938x high fidelity audio codec and WSA881x speaker amp on carrier board Dedicated Hexagon audio DSP SoundWire, MI2S, DMIC, TDM/PCM interfaces for audio devices on carrier board		
· High Speed Connectivity	1x PCle Gen3 2-lane 1x USB 3.1 with support for Type-C + DisplayPort v1.4 with USB SS data concurrency 1x USB 3.1 Type-A		
• I/O Interfaces	4-bit SD 3.0, UART, I2C, I3C, SPI, configurable GPIOs, sensor I/O to dedicated Hexagon sensor DSP		
• Power/Battery	Power management and battery charging solution on SOM		
Operating Environment	Input voltage: 3.7V nominal Operating Temperature: 25°C to +85°C Tc (component case temperature)		
• Form Factor	50mm x 29mm with 2x 100-pin + 1x 120-pin board to board connectors		

#### Software:

OS Support	Android™ 10 — Note that all hardware features may not be supported by SW



### **Purchasing Information:**

• Open-Q™ 865XR SOM (6+64GB)	PN: QC-DB-U10004
• Open-Q <sup>™</sup> 865XR SOM (8+128GB)	PN: QC-DB-U10004A

Alternate SOM configurations available by special order (minimum order quantities apply) e.g. different memory size, etc. Contact sales to discuss your specific needs today.

#### **Companion Development Kit Available Separately**

#### Certifications







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